

L Number	Hits	Search Text	DB	Time stamp
2	4	photoimageable and (((photoimageable glass sin sio2 sio son (silicon adj3 (dioxide nitride oxynitride))) with spacer) same (semiconductor chip die (integrated adj circuit) ic dice flipchip (flip adj chip))) same (stack stacking stacked plurality multi multiple assembly))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 14:52
1	583	((photoimageable glass sin sio2 sio son (silicon adj3 (dioxide nitride oxynitride))) with spacer) same (semiconductor chip die (integrated adj circuit) ic dice flipchip (flip adj chip))) same (stack stacking stacked plurality multi multiple assembly)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 15:29
3	2595	photoresist with spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 15:30
4	7379	photoresist with polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 15:32
5	9938	photoresist with (polyimide polymer polymide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 15:31
6	13918	photoresist with poly\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 15:34
7	157	(photoresist with (polyimide polymer polymide)) with spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 15:34